

**Version With Markings to Show Changes Made**

In the Claims

Claim 13 has been amended as follows:

13. (Four times amended) A tape for [manufacturing] semiconductor devices,  
said tape comprising:

a single dielectric layer having openings;

electrically conductive leads associated with said openings, said leads being printed  
on said dielectric layer; and

a low temperature curing adhesive material that cures to about ninety percent of its  
maximum strength within two to three hours without exceeding one hundred fifty degrees  
Fahrenheit, said low temperature curing adhesive material being located between [said] a  
semiconductor chip and said dielectric layer.

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